

#4 11-22-00
Rae Ault A

Case No.: DENSE-015X

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: DENSE-PAC MICROSYSTEMS, INC.)
Patent No.: 5,869,353)
Issued: FEBRUARY 9, 1999)
For: MODULAR PANEL STACKING PROCESS)

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D. C. 20231

Dear Sir/Madam:

Prior to the initial examination of the subject reissue patent application, please enter the following Preliminary Amendment.

IN THE CLAIMS:

Please add the following new claims into prosecution:

7. - (New) A chip stack comprising:
at least two packaged chips, each of the packaged chips having opposite sides and a
multiplicity of leads extending from each of the opposite sides thereof; and
at least one frame extending along at least each of the opposite sides of the packaged
chips and comprising: